

THAT WHICH IS CLAIMED IS:

1. A method of mounting an electronic component which has at least one contact extending across a part of the undersurface of the electronic component, the method comprising:

- 5 providing a support which is smaller in area than the undersurface of the electronic component, the support having a contact pad for connection to said contact, the contact pad having a first portion extending across an upper surface of the support
- 10 adjacent on edge thereof and a second portion extending from said edge across a side surface of the support; positioning the electronic component and the support with the under surface of the electronic component adjacent the upper surface of the support such that the
- 15 first portion of the contact pad is aligned with and spaced from a first portion of the contact and the second portion of the contact pad is aligned with and disposed inwardly of a second portion of the contact; and
- 20 forming a solder connection between the contact and the contact pad, the solder connection comprising a generally planar portion between the first portions of the contact and the contact pad, and a fillet portion extending angularly from the second
- 25 portion of the contact to the second portion of the contact pad.

2. The method of Claim 1, in which the solder connection is formed by placing solder paste between the contact and the contact pad, and heating the assembly to cause flow of the solder paste.

3. The method of Claim 2, in which the electronic component is held upside down, the solder paste is applied to the electronic component, the support is applied upside down to the solder paste, and
5 the assembly is heated.

4. The method of Claim 3, in which the assembly is maintained upside down until it is cooled.

5. The method of any preceding claim, in which the electronic component is an integrated circuit having a plurality of contacts, at least part of each contact extending across a part of the under surface of
5 the integrated circuit; and the support is a printed circuit board which includes a contact portion for each of said contacts.

6. The combination of an integrated circuit and a printed circuit board, in which the printed circuit board is smaller in area than the integrated circuit.

7. The combination of Claim 6, in which the printed circuit board has a number of contact pads which each have a first portion extending across an upper surface of the printed circuit board adjacent on
5 edge thereof and a second portion extending from said edge across a side surface of the printed circuit board; the integrated circuit has a corresponding number of contacts each of which has at least a part thereof extending across part of the undersurface of
10 the integrated circuit; and each contact is connected

to a respective contact pad by a solder connection which includes a fillet portion.

8. A printed circuit board for use in the combination of Claim 6 or Claim 7, the printed circuit board including contacts each of which has a portion extending across a side face of the printed circuit
5 board.

9. A method for making the printed circuit board of Claim 8, the method including the steps of forming one or more plated through-holes, and cutting the board along a path which passes through said
5 hole(s).